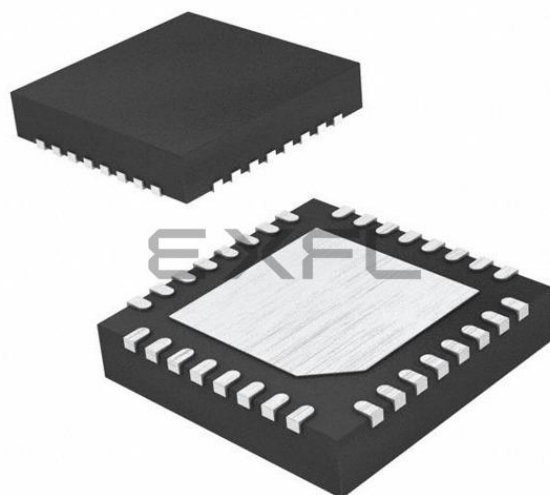




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Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64mc502t-i-mm

4.2 Data Address Space

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a separate 16-bit-wide data memory space. The Data Space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps, which are presented by device family and memory size, are shown in Figure 4-7 through Figure 4-16.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the Data Space. This arrangement gives a base Data Space address range of 64 Kbytes (32K words).

The base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space, which has a total address range of 16 Mbytes.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement up to 52 Kbytes of data memory (4 Kbytes of data memory for Special Function Registers and up to 48 Kbytes of data memory for RAM). If an EA points to a location outside of this area, an all-zero word or byte is returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit-wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve Data Space memory usage efficiency, the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 4 Kbytes of the Near Data Space, from 0x0000 to 0x0FFF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note: The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable through a 13-bit absolute address field within all memory direct instructions. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an Address Pointer.

TABLE 4-29: PERIPHERAL PIN SELECT INPUT REGISTER MAP FOR PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets		
RPINR0	06A0	—	INT1R<6:0>								—	—	—	—	—	—	—	—	0000	
RPINR1	06A2	—	—	—	—	—	—	—	—	—	INT2R<6:0>								0000	
RPINR3	06A6	—	—	—	—	—	—	—	—	—	T2CKR<6:0>								0000	
RPINR7	06AE	—	IC2R<6:0>								—	IC1R<6:0>								0000
RPINR8	06B0	—	IC4R<6:0>								—	IC3R<6:0>								0000
RPINR11	06B6	—	—	—	—	—	—	—	—	—	OCFAR<6:0>								0000	
RPINR12	06B8	—	FLT2R<6:0>								—	FLT1R<6:0>								0000
RPINR14	06BC	—	QEB1R<6:0>								—	QEA1R<6:0>								0000
RPINR15	06BE	—	HOME1R<6:0>								—	INDX1R<6:0>								0000
RPINR18	06C4	—	—	—	—	—	—	—	—	—	U1RXR<6:0>								0000	
RPINR19	06C6	—	—	—	—	—	—	—	—	—	U2RXR<6:0>								0000	
RPINR22	06CC	—	SCK2INR<6:0>								—	SDI2R<6:0>								0000
RPINR23	06CE	—	—	—	—	—	—	—	—	—	SS2R<6:0>								0000	
RPINR26	06D4	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000		
RPINR37	06EA	—	SYNCI1R<6:0>								—	—	—	—	—	—	—	—	0000	
RPINR38	06EC	—	DTCMP1R<6:0>								—	—	—	—	—	—	—	—	0000	
RPINR39	06EE	—	DTCMP3R<6:0>								—	DTCMP2R<6:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-30: PERIPHERAL PIN SELECT INPUT REGISTER MAP FOR PIC24EPXXXGP20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets		
RPINR0	06A0	—	INT1R<6:0>								—	—	—	—	—	—	—	—	0000	
RPINR1	06A2	—	—	—	—	—	—	—	—	—	INT2R<6:0>								0000	
RPINR3	06A6	—	—	—	—	—	—	—	—	—	T2CKR<6:0>								0000	
RPINR7	06AE	—	IC2R<6:0>								—	IC1R<6:0>								0000
RPINR8	06B0	—	IC4R<6:0>								—	IC3R<6:0>								0000
RPINR11	06B6	—	—	—	—	—	—	—	—	—	OCFAR<6:0>								0000	
RPINR18	06C4	—	—	—	—	—	—	—	—	—	U1RXR<6:0>								0000	
RPINR19	06C6	—	—	—	—	—	—	—	—	—	U2RXR<6:0>								0000	
RPINR22	06CC	—	SCK2INR<6:0>								—	SDI2R<6:0>								0000
RPINR23	06CE	—	—	—	—	—	—	—	—	—	SS2R<6:0>								0000	

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-45: DMAC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
DMA0CON	0B00	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA0REQ	0B02	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA0STAL	0B04	STA<15:0>																	0000
DMA0STAH	0B06	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA0STBL	0B08	STB<15:0>																	0000
DMA0STBH	0B0A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA0PAD	0B0C	PAD<15:0>																	0000
DMA0CNT	0B0E	—	—	CNT<13:0>															0000
DMA1CON	0B10	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA1REQ	0B12	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA1STAL	0B14	STA<15:0>																	0000
DMA1STAH	0B16	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA1STBL	0B18	STB<15:0>																	0000
DMA1STBH	0B1A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA1PAD	0B1C	PAD<15:0>																	0000
DMA1CNT	0B1E	—	—	CNT<13:0>															0000
DMA2CON	0B20	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA2REQ	0B22	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA2STAL	0B24	STA<15:0>																	0000
DMA2STAH	0B26	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA2STBL	0B28	STB<15:0>																	0000
DMA2STBH	0B2A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA2PAD	0B2C	PAD<15:0>																	0000
DMA2CNT	0B2E	—	—	CNT<13:0>															0000
DMA3CON	0B30	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA3REQ	0B32	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA3STAL	0B34	STA<15:0>																	0000
DMA3STAH	0B36	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA3STBL	0B38	STB<15:0>																	0000
DMA3STBH	0B3A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA3PAD	0B3C	PAD<15:0>																	0000
DMA3CNT	0B3E	—	—	CNT<13:0>															0000
DMA3PWC	0BF0	—	—	—	—	—	—	—	—	—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0	0000	
DMA3RQC	0BF2	—	—	—	—	—	—	—	—	—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0	0000	
DMA3PPS	0BF4	—	—	—	—	—	—	—	—	—	—	—	—	PPST3	PPST2	PPST1	PPST0	0000	
DMA3LCA	0BF6	—	—	—	—	—	—	—	—	—	—	—	—	LSTCH<3:0>				000F	
DSADRL	0BF8	DSADR<15:0>																	0000
DSADRH	0BFA	—	—	—	—	—	—	—	—	DSADR<23:16>									0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES

Peripheral Pin Select Input Register Value	Input/Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/Output	Pin Assignment
000 0000	I	Vss	010 1101	I	RPI45
000 0001	I	C1OUT ⁽¹⁾	010 1110	I	RPI46
000 0010	I	C2OUT ⁽¹⁾	010 1111	I	RPI47
000 0011	I	C3OUT ⁽¹⁾	011 0000	—	—
000 0100	I	C4OUT ⁽¹⁾	011 0001	—	—
000 0101	—	—	011 0010	—	—
000 0110	I	PTGO30 ⁽¹⁾	011 0011	I	RPI51
000 0111	I	PTGO31 ⁽¹⁾	011 0100	I	RPI52
000 1000	I	FINDX1 ^(1,2)	011 0101	I	RPI53
000 1001	I	FHOME1 ^(1,2)	011 0110	I/O	RP54
000 1010	—	—	011 0111	I/O	RP55
000 1011	—	—	011 1000	I/O	RP56
000 1100	—	—	011 1001	I/O	RP57
000 1101	—	—	011 1010	I	RPI58
000 1110	—	—	011 1011	—	—
000 1111	—	—	011 1100	—	—
001 0000	—	—	011 1101	—	—
001 0001	—	—	011 1110	—	—
001 0010	—	—	011 1111	—	—
001 0011	—	—	100 0000	—	—
001 0100	I/O	RP20	100 0001	—	—
001 0101	—	—	100 0010	—	—
001 0110	—	—	100 0011	—	—
001 0111	—	—	100 0100	—	—
001 1000	I	RPI24	100 0101	—	—
001 1001	I	RPI25	100 0110	—	—
001 1010	—	—	100 0111	—	—
001 1011	I	RPI27	100 1000	—	—
001 1100	I	RPI28	100 1001	—	—
001 1101	—	—	100 1010	—	—
001 1110	—	—	100 1011	—	—
001 1111	—	—	100 1100	—	—
010 0000	I	RPI32	100 1101	—	—
010 0001	I	RPI33	100 1110	—	—
010 0010	I	RPI34	100 1111	—	—
010 0011	I/O	RP35	101 0000	—	—
010 0100	I/O	RP36	101 0001	—	—
010 0101	I/O	RP37	101 0010	—	—
010 0110	I/O	RP38	101 0011	—	—
010 0111	I/O	RP39	101 0100	—	—

Legend: Shaded rows indicate PPS Input register values that are unimplemented.

Note 1: See Section 11.4.4.1 “Virtual Connections” for more information on selecting this pin assignment.

2: These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

11.5 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 30-11, under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins, with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note: Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUs and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to $\sim(VDD - 0.8)$, not VDD. This value is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specification. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:
 $VOH = 2.4V @ IOH = -8\text{ mA and }VDD = 3.3V$
 The maximum output current sourced by any 8 mA I/O pin = 12 mA.
 LED source current < 12 mA is technically permitted. Refer to the VOH/IOH graphs in **Section 30.0 “Electrical Characteristics”** for additional information.
6. The Peripheral Pin Select (PPS) pin mapping rules are as follows:
 - a) Only one “output” function can be active on a given pin at any time, regardless if it is a dedicated or remappable function (one pin, one output).
 - b) It is possible to assign a “remappable output” function to multiple pins and externally short or tie them together for increased current drive.
 - c) If any “dedicated output” function is enabled on a pin, it will take precedence over any remappable “output” function.
 - d) If any “dedicated digital” (input or output) function is enabled on a pin, any number of “input” remappable functions can be mapped to the same pin.
 - e) If any “dedicated analog” function(s) are enabled on a given pin, “digital input(s)” of any kind will all be disabled, although a single “digital output”, at the user’s cautionary discretion, can be enabled and active as long as there is no signal contention with an external analog input signal. For example, it is possible for the ADC to convert the digital output logic level, or to toggle a digital output on a comparator or ADC input provided there is no external analog input, such as for a built-in self-test.
 - f) Any number of “input” remappable functions can be mapped to the same pin(s) at the same time, including to any pin with a single output from either a dedicated or remappable “output”.

REGISTER 16-12: TRGCONx: PWMx TRIGGER CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
TRGDIV<3:0>				—	—	—	—
bit 15				bit 8			

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TRGSTRT<5:0> ⁽¹⁾					
bit 7		bit 0					

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-12 **TRGDIV<3:0>**: Trigger # Output Divider bits

1111 = Trigger output for every 16th trigger event
 1110 = Trigger output for every 15th trigger event
 1101 = Trigger output for every 14th trigger event
 1100 = Trigger output for every 13th trigger event
 1011 = Trigger output for every 12th trigger event
 1010 = Trigger output for every 11th trigger event
 1001 = Trigger output for every 10th trigger event
 1000 = Trigger output for every 9th trigger event
 0111 = Trigger output for every 8th trigger event
 0110 = Trigger output for every 7th trigger event
 0101 = Trigger output for every 6th trigger event
 0100 = Trigger output for every 5th trigger event
 0011 = Trigger output for every 4th trigger event
 0010 = Trigger output for every 3rd trigger event
 0001 = Trigger output for every 2nd trigger event
 0000 = Trigger output for every trigger event

bit 11-6 **Unimplemented**: Read as '0'

bit 5-0 **TRGSTRT<5:0>**: Trigger Postscaler Start Enable Select bits⁽¹⁾

111111 = Waits 63 PWM cycles before generating the first trigger event after the module is enabled
 •
 •
 •

000010 = Waits 2 PWM cycles before generating the first trigger event after the module is enabled
 000001 = Waits 1 PWM cycle before generating the first trigger event after the module is enabled
 000000 = Waits 0 PWM cycles before generating the first trigger event after the module is enabled

Note 1: The secondary PWM generator cannot generate PWMx trigger interrupts.

REGISTER 17-2: QEI1IOC: QEI1 I/O CONTROL REGISTER (CONTINUED)

bit 2	INDEX: Status of INDXx Input Pin After Polarity Control 1 = Pin is at logic '1' 0 = Pin is at logic '0'
bit 1	QEB: Status of QEBx Input Pin After Polarity Control And SWPAB Pin Swapping 1 = Pin is at logic '1' 0 = Pin is at logic '0'
bit 0	QEA: Status of QEAx Input Pin After Polarity Control And SWPAB Pin Swapping 1 = Pin is at logic '1' 0 = Pin is at logic '0'

REGISTER 21-11: CxFEN1: ECANx ACCEPTANCE FILTER ENABLE REGISTER 1

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **FLTEN<15:0>**: Enable Filter n to Accept Messages bits
 1 = Enables Filter n
 0 = Disables Filter n

REGISTER 21-12: CxBUFNT1: ECANx FILTER 0-3 BUFFER POINTER REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F3BP<3:0>				F2BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F1BP<3:0>				F0BP<3:0>			
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-12 **F3BP<3:0>**: RX Buffer Mask for Filter 3 bits
 1111 = Filter hits received in RX FIFO buffer
 1110 = Filter hits received in RX Buffer 14
 .
 .
 .
 0001 = Filter hits received in RX Buffer 1
 0000 = Filter hits received in RX Buffer 0
 bit 11-8 **F2BP<3:0>**: RX Buffer Mask for Filter 2 bits (same values as bits<15:12>)
 bit 7-4 **F1BP<3:0>**: RX Buffer Mask for Filter 1 bits (same values as bits<15:12>)
 bit 3-0 **F0BP<3:0>**: RX Buffer Mask for Filter 0 bits (same values as bits<15:12>)

21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID10	SID9	SID8	SID7	SID6
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'
 bit 12-2 **SID<10:0>:** Standard Identifier bits
 bit 1 **SRR:** Substitute Remote Request bit
 When IDE = 0:
 1 = Message will request remote transmission
 0 = Normal message
 When IDE = 1:
 The SRR bit must be set to '1'.
 bit 0 **IDE:** Extended Identifier bit
 1 = Message will transmit Extended Identifier
 0 = Message will transmit Standard Identifier

BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID17	EID16	EID15	EID14
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'
 bit 11-0 **EID<17:6>:** Extended Identifier bits

23.4 ADC Control Registers

REGISTER 23-1: AD1CON1: ADC1 CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	ADDMAABM	—	AD12B	FORM1	FORM0
bit 15						bit 8	

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0, HC, HS	R/C-0, HC, HS
SSRC2	SSRC1	SSRC0	SSRCG	SIMSAM	ASAM	SAMP	DONE ⁽³⁾
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	C = Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

- bit 15 **ADON:** ADC1 Operating Mode bit
 1 = ADC module is operating
 0 = ADC is off
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **ADSIDL:** ADC1 Stop in Idle Mode bit
 1 = Discontinues module operation when device enters Idle mode
 0 = Continues module operation in Idle mode
- bit 12 **ADDMAABM:** DMA Buffer Build Mode bit
 1 = DMA buffers are written in the order of conversion; the module provides an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer
 0 = DMA buffers are written in Scatter/Gather mode; the module provides a Scatter/Gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer.
- bit 11 **Unimplemented:** Read as '0'
- bit 10 **AD12B:** ADC1 10-Bit or 12-Bit Operation Mode bit
 1 = 12-bit, 1-channel ADC operation
 0 = 10-bit, 4-channel ADC operation
- bit 9-8 **FORM<1:0>:** Data Output Format bits
 For 10-Bit Operation:
 11 = Signed fractional (DOUT = sddd dddd dd00 0000, where s = .NOT.d<9>)
 10 = Fractional (DOUT = dddd dddd dd00 0000)
 01 = Signed integer (DOUT = ssss sssd dddd dddd, where s = .NOT.d<9>)
 00 = Integer (DOUT = 0000 00dd dddd dddd)
 For 12-Bit Operation:
 11 = Signed fractional (DOUT = sddd dddd dddd 0000, where s = .NOT.d<11>)
 10 = Fractional (DOUT = dddd dddd dddd 0000)
 01 = Signed integer (DOUT = ssss sddd dddd dddd, where s = .NOT.d<11>)
 00 = Integer (DOUT = 0000 dddd dddd dddd)

- Note 1:** See Section 24.0 “Peripheral Trigger Generator (PTG) Module” for information on this selection.
- 2:** This setting is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
- 3:** Do not clear the DONE bit in software if Auto-Sample is enabled (ASAM = 1).

REGISTER 23-6: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER (CONTINUED)

bit 4-0 **CH0SA<4:0>**: Channel 0 Positive Input Select for Sample MUXA bits⁽¹⁾

11111 = Open; use this selection with CTMU capacitive and time measurement
 11110 = Channel 0 positive input is connected to the CTMU temperature measurement diode (CTMU TEMP)
 11101 = Reserved
 11100 = Reserved
 11011 = Reserved
 11010 = Channel 0 positive input is the output of OA3/AN6^(2,3)
 11001 = Channel 0 positive input is the output of OA2/AN0⁽²⁾
 11000 = Channel 0 positive input is the output of OA1/AN3⁽²⁾
 10110 = Reserved
 •
 •
 •
 10000 = Reserved
 01111 = Channel 0 positive input is AN15^(1,3)
 01110 = Channel 0 positive input is AN14^(1,3)
 01101 = Channel 0 positive input is AN13^(1,3)
 •
 •
 •
 00010 = Channel 0 positive input is AN2^(1,3)
 00001 = Channel 0 positive input is AN1^(1,3)
 00000 = Channel 0 positive input is AN0^(1,3)

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

3: See the “Pin Diagrams” section for the available analog channels for each device.

REGISTER 24-3: PTGBTE: PTG BROADCAST TRIGGER ENABLE REGISTER^(1,2) (CONTINUED)

- bit 4 **OC1CS:** Clock Source for OC1 bit
1 = Generates clock pulse when the broadcast command is executed
0 = Does not generate clock pulse when the broadcast command is executed
- bit 3 **OC4TSS:** Trigger/Synchronization Source for OC4 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed
- bit 2 **OC3TSS:** Trigger/Synchronization Source for OC3 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed
- bit 1 **OC2TSS:** Trigger/Synchronization Source for OC2 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed
- bit 0 **OC1TSS:** Trigger/Synchronization Source for OC1 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

2: This register is only used with the PTGCTRL OPTION = 1111 Step command.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected
72	SL	SL f	f = Left Shift f	1	1	C,N,OV,Z
		SL f, WREG	WREG = Left Shift f	1	1	C,N,OV,Z
		SL ws, wd	Wd = Left Shift Ws	1	1	C,N,OV,Z
		SL wb, wns, wnd	Wnd = Left Shift Wb by Wns	1	1	N,Z
		SL wb, #lit5, wnd	Wnd = Left Shift Wb by lit5	1	1	N,Z
73	SUB	SUB Acc ⁽¹⁾	Subtract Accumulators	1	1	OA,OB,OAB,SA,SB,SAB
		SUB f	f = f – WREG	1	1	C,DC,N,OV,Z
		SUB f, WREG	WREG = f – WREG	1	1	C,DC,N,OV,Z
		SUB #lit10, wn	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		SUB wb, ws, wd	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		SUB wb, #lit5, wd	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
74	SUBB	SUBB f	f = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB f, WREG	WREG = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB #lit10, wn	Wn = Wn – lit10 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB wb, ws, wd	Wd = Wb – Ws – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB wb, #lit5, wd	Wd = Wb – lit5 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
75	SUBR	SUBR f	f = WREG – f	1	1	C,DC,N,OV,Z
		SUBR f, WREG	WREG = WREG – f	1	1	C,DC,N,OV,Z
		SUBR wb, ws, wd	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		SUBR wb, #lit5, wd	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
76	SUBBR	SUBBR f	f = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR f, WREG	WREG = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR wb, ws, wd	Wd = Ws – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR wb, #lit5, wd	Wd = lit5 – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
77	SWAP	SWAP.b wn	Wn = nibble swap Wn	1	1	None
		SWAP wn	Wn = byte swap Wn	1	1	None
78	TBLRDH	TBLRDH ws, wd	Read Prog<23:16> to Wd<7:0>	1	5	None
79	TBLRDL	TBLRDL ws, wd	Read Prog<15:0> to Wd	1	5	None
80	TBLWTH	TBLWTH ws, wd	Write Ws<7:0> to Prog<23:16>	1	2	None
81	TBLWTL	TBLWTL ws, wd	Write Ws to Prog<15:0>	1	2	None
82	ULNK	ULNK	Unlink Frame Pointer	1	1	SFA
83	XOR	XOR f	f = f .XOR. WREG	1	1	N,Z
		XOR f, WREG	WREG = f .XOR. WREG	1	1	N,Z
		XOR #lit10, wn	Wd = lit10 .XOR. Wd	1	1	N,Z
		XOR wb, ws, wd	Wd = Wb .XOR. Ws	1	1	N,Z
		XOR wb, #lit5, wd	Wd = Wb .XOR. lit5	1	1	N,Z
84	ZE	ZE ws, wnd	Wnd = Zero-extend Ws	1	1	C,Z,N

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

FIGURE 30-2: EXTERNAL CLOCK TIMING

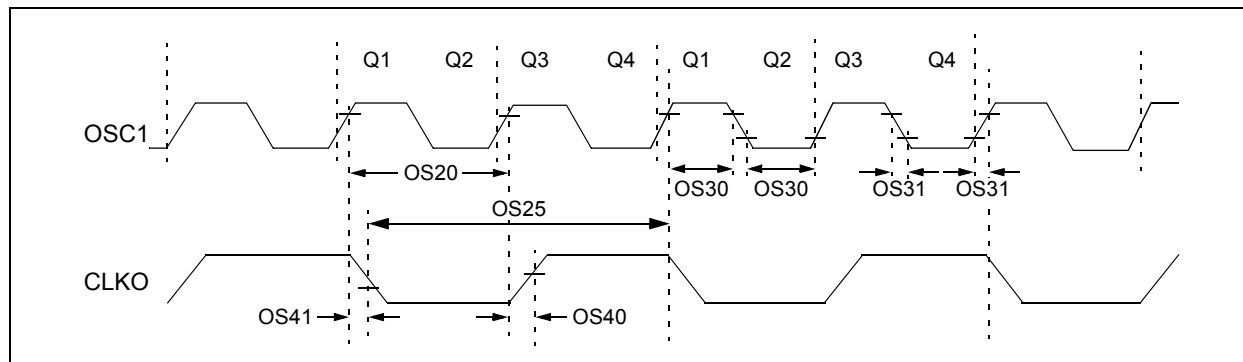


TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symb	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	60	MHz	EC
		Oscillator Crystal Frequency	3.5 10	— —	10 25	MHz MHz	XT HS
OS20	Tosc	Tosc = 1/Fosc	8.33	—	DC	ns	+125°C
		Tosc = 1/Fosc	7.14	—	DC	ns	+85°C
OS25	Tcy	Instruction Cycle Time ⁽²⁾	16.67	—	DC	ns	+125°C
		Instruction Cycle Time ⁽²⁾	14.28	—	DC	ns	+85°C
OS30	TosL, TosH	External Clock in (OSC1) High or Low Time	0.45 x Tosc	—	0.55 x Tosc	ns	EC
OS31	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time ^(3,4)	—	5.2	—	ns	
OS41	TckF	CLKO Fall Time ^(3,4)	—	5.2	—	ns	
OS42	GM	External Oscillator Transconductance ⁽⁴⁾	—	12	—	mA/V	HS, VDD = 3.3V, TA = +25°C
			—	6	—	mA/V	XT, VDD = 3.3V, TA = +25°C

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

- 2:** Instruction cycle period (Tcy) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “Minimum” values with an external clock applied to the OSC1 pin. When an external clock input is used, the “Maximum” cycle time limit is “DC” (no clock) for all devices.
- 3:** Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.
- 4:** This parameter is characterized, but not tested in manufacturing.

FIGURE 30-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS

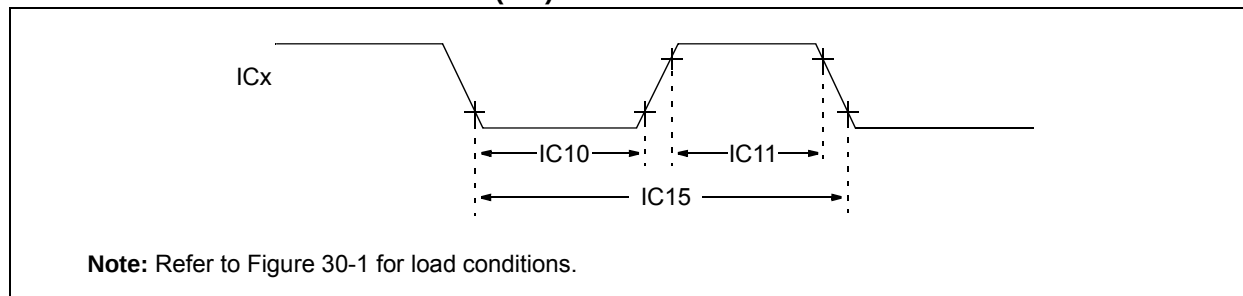
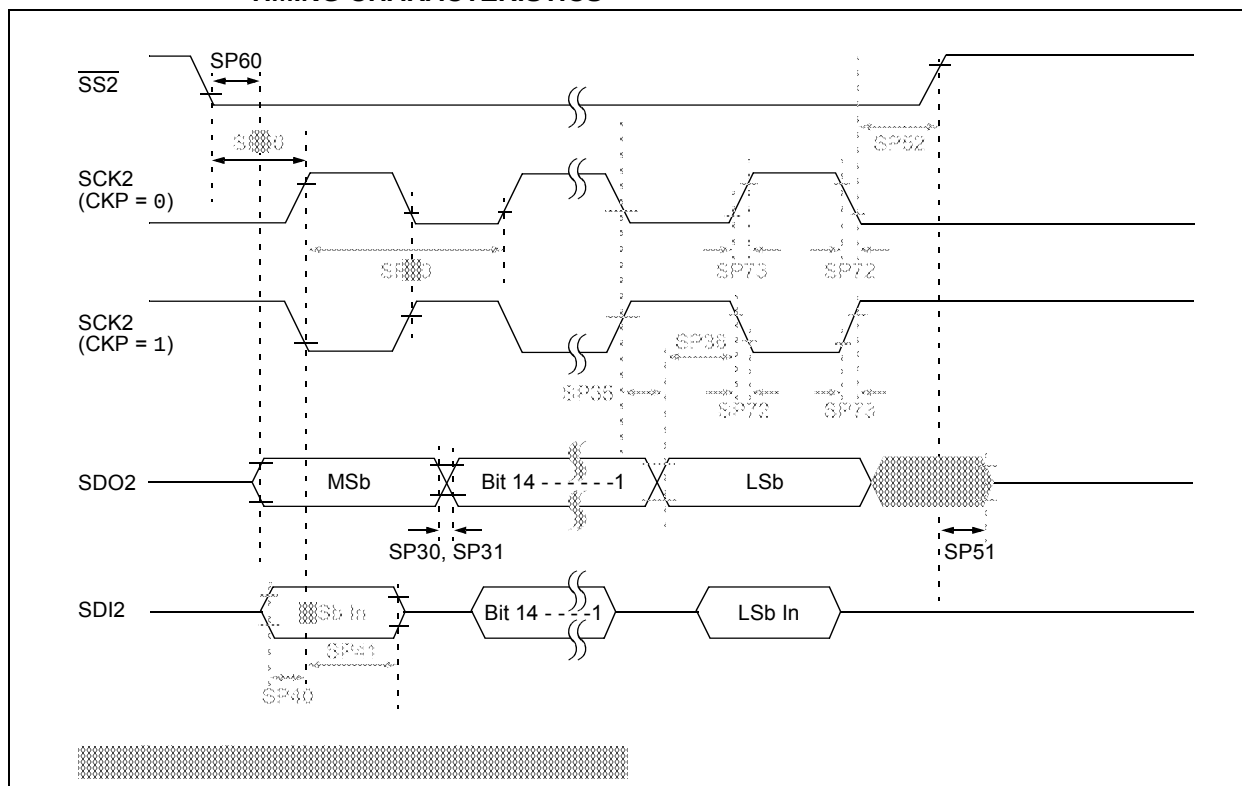


TABLE 30-26: INPUT CAPTURE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Max.	Units	Conditions	
IC10	TccL	ICx Input Low Time	Greater of $12.5 + 25$ or $(0.5 T_{CY}/N) + 25$	—	ns	Must also meet Parameter IC15	N = prescale value (1, 4, 16)
IC11	TccH	ICx Input High Time	Greater of $12.5 + 25$ or $(0.5 T_{CY}/N) + 25$	—	ns	Must also meet Parameter IC15	
IC15	TccP	ICx Input Period	Greater of $25 + 50$ or $(1 T_{CY}/N) + 50$	—	ns		

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-18: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0)
TIMING CHARACTERISTICS



**TABLE 30-48: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK1 Input Frequency	—	—	11	MHz	(Note 3)
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1} \downarrow$ to SCK1 $\uparrow$ or SCK1 $\downarrow$ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1} \uparrow$ to SDO1 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH, TscL2ssH	$\overline{SS1} \uparrow$ after SCK1 Edge	1.5 TCY + 40	—	—	ns	(Note 4)

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS

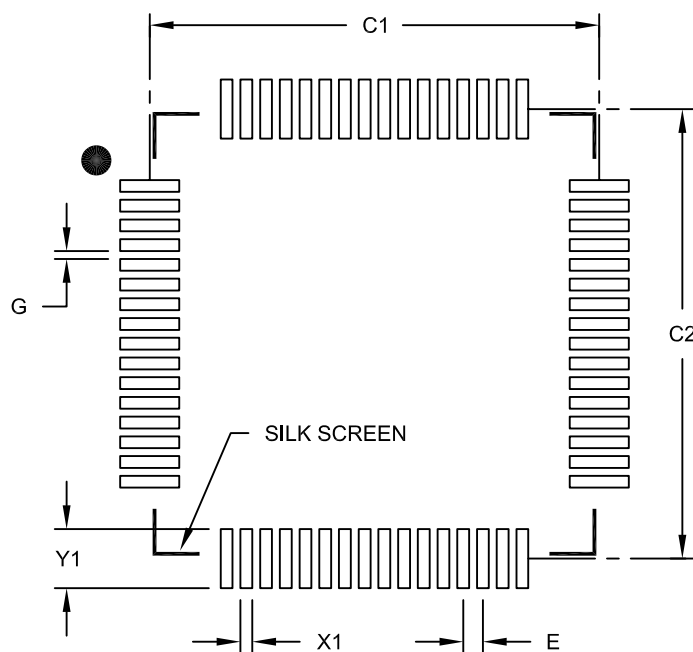
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
Comparator AC Characteristics							
CM10	TRESP	Response Time ⁽³⁾	—	19	—	ns	V+ input step of 100 mV, V- input held at VDD/2
CM11	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	μs	
Comparator DC Characteristics							
CM30	VOFFSET	Comparator Offset Voltage	—	±10	40	mV	
CM31	VHYST	Input Hysteresis Voltage ⁽³⁾	—	30	—	mV	
CM32	TRISE/ TFALL	Comparator Output Rise/ Fall Time ⁽³⁾	—	20	—	ns	1 pF load capacitance on input
CM33	VGAIN	Open-Loop Voltage Gain ⁽³⁾	—	90	—	db	
CM34	VICM	Input Common-Mode Voltage	AVSS	—	AVDD	V	
Op Amp AC Characteristics							
CM20	SR	Slew Rate ⁽³⁾	—	9	—	V/μs	10 pF load
CM21a	PM	Phase Margin (Configuration A) ^(3,4)	—	55	—	Degree	G = 100V/V; 10 pF load
CM21b	PM	Phase Margin (Configuration B) ^(3,5)	—	40	—	Degree	G = 100V/V; 10 pF load
CM22	GM	Gain Margin ⁽³⁾	—	20	—	db	G = 100V/V; 10 pF load
CM23a	GBW	Gain Bandwidth (Configuration A) ^(3,4)	—	10	—	MHz	10 pF load
CM23b	GBW	Gain Bandwidth (Configuration B) ^(3,5)	—	6	—	MHz	10 pF load

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

- 2:** Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.
- 3:** Parameter is characterized but not tested in manufacturing.
- 4:** See Figure 25-6 for configuration information.
- 5:** See Figure 25-7 for configuration information.
- 6:** Resistances can vary by ±10% between op amps.

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 16.0 “High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)”	Updated the High-Speed PWM Module Register Interconnection Diagram (see Figure 16-2). Added the TRGCONx and TRIGx registers (see Register 16-12 and Register 16-14, respectively).
Section 21.0 “Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)”	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 22.0 “Charge Time Measurement Unit (CTMU)”	Updated the IRNG<1:0> bit value definitions and added Note 2 in the CTMU Current Control Register (see Register 22-3).
Section 25.0 “Op amp/Comparator Module”	Updated the Op amp/Comparator I/O Operating Modes Diagram (see Figure 25-1). Updated the User-programmable Blanking Function Block Diagram (see Figure 25-3). Updated the Digital Filter Interconnect Block Diagram (see Figure 25-4). Added Section 25.1 “Op amp Application Considerations” . Added Note 2 to the Comparator Control Register (see Register 25-2). Updated the bit definitions in the Comparator Mask Gating Control Register (see Register 25-5).
Section 27.0 “Special Features”	Updated the FICD Configuration Register, updated Note 1, and added Note 3 in the Configuration Byte Register Map (see Table 27-1). Added Section 27.2 “User ID Words” .
Section 30.0 “Electrical Characteristics”	Updated the following Absolute Maximum Ratings: - Maximum current out of VSS pin - Maximum current into VDD pin Added Note 1 to the Operating MIPS vs. Voltage (see Table 30-1). Updated all Idle Current (IDLE) Typical and Maximum DC Characteristics values (see Table 30-7). Updated all Doze Current (IDOZE) Typical and Maximum DC Characteristics values (see Table 30-9). Added Note 2, removed Parameter CM24, updated the Typical values Parameters CM10, CM20, CM21, CM32, CM41, CM44, and CM45, and updated the Minimum values for CM40 and CM41, and the Maximum value for CM40 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Updated Note 2 and the Typical value for Parameter VR310 in the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Note 1, removed Parameter VRD312, and added Parameter VRD314 to the Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated the Minimum, Typical, and Maximum values for Internal LPRC Accuracy (see Table 30-22). Updated the Minimum, Typical, and Maximum values for Parameter SY37 in the Reset, Watchdog Timer, Oscillator Start-up Timer, Power-up Timer Timing Requirements (see Table 30-24). The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-35)